

Description

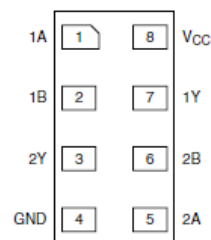
The Advanced Ultra Low Power (AUP) CMOS logic family is designed for low power and extended battery life in portable applications.

The 74AUP2G86 is a dual two-input EXCLUSIVE OR gate. Both gates have push-pull outputs designed for operation over a power supply range of 0.8V to 3.6V. The device is fully specified for partial power down applications using I_{OFF}. The I_{OFF} circuitry disables the output preventing damaging current backflow when the device is powered down. Each gate performs the positive Boolean function:

$$Y = A \oplus B \text{ or } Y = \overline{A}B + A\overline{B}$$

Pin Assignments

(Top View)



X2-DFN1210-8

Features

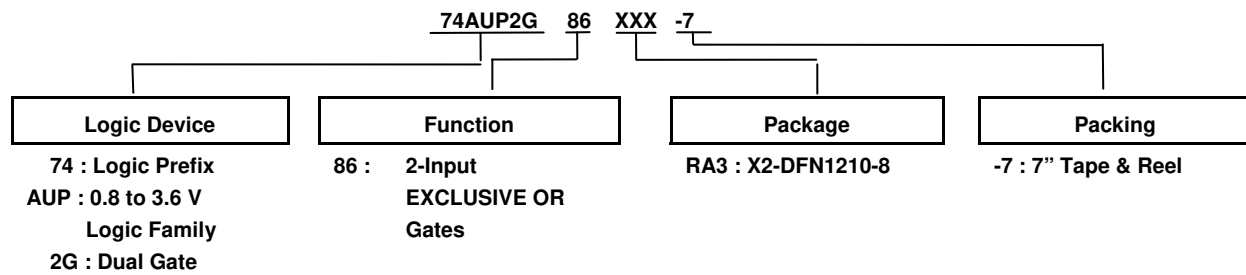
- Advanced Ultra Low Power (AUP) CMOS
- Supply Voltage Range from 0.8V to 3.6V
- ±4mA Output Drive at 3.0V
- Low Static Power Consumption
I_{CC} < 0.9µA
- Low Dynamic Power Consumption
C_{PD} = 6 pF (Typical at 3.6V)
- Schmitt Trigger Action at all inputs makes the circuit tolerant for slower input rise and fall time. The hysteresis is typically 250 mV at V_{CC} = 3.0V
- I_{OFF} Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
2000-V Human Body Model (A114)
Exceeds 1000-V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- Leadless Packages Named per JESD30E
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. “Green” Device (Note 3)**

Applications

- Suited for Battery and Low Power Needs
- Wide array of products such as:
 - Tablets, E-readers
 - Cell Phones, Personal Navigation/GPS
 - MP3 Players, Cameras, Video Recorders
 - PCs, Ultrabooks, Notebooks, Netbooks
 - Computer Peripherals, Hard Drives, SSD, CD/DVD ROM
 - TV, DVD, DVR, Set-Top Box

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Ordering Information



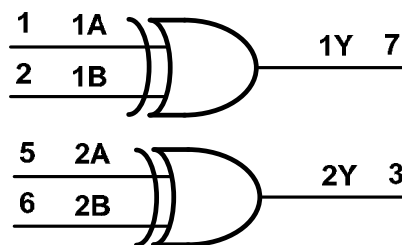
Device	Package Code	Package (Notes 4 & 5)	Package Size	7" Tape and Reel	
				Quantity	Part Number Suffix
74AUP2G86RA3-7	RA3	X2-DFN1210-8	1.2mm x 1.0mm x 0.35mm 0.3 mm lead pitch	5,000/Tape & Reel	-7

Notes: 4. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
5. The taping orientation is located on our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Pin Descriptions

Pin Name	Pin	Function
1A	1	Data Input
1B	2	Data Input
2Y	3	Data Output
GND	4	Ground
2A	5	Data Input
2B	6	Data Input
1Y	7	Data Output
V _{CC}	8	Supply Voltage

Logic Diagram



Function Table

Inputs		Output
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	L

Absolute Maximum Ratings (Notes 6 & 7)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V_{CC}	Supply Voltage Range	-0.5 to +4.6	V
V_I	Input Voltage Range	-0.5 to +4.6	V
V_O	Voltage Applied to Output in High or Low State	-0.5 to $V_{CC} + 0.5$	V
I_{IK}	Input Clamp Current $V_I < 0$	50	mA
I_{OK}	Output Clamp Current ($V_O < 0$)	50	mA
I_O	Continuous Output Current ($V_O = 0$ to V_{CC})	± 20	mA
I_{CC}	Continuous Current Through V_{CC}	50	mA
I_{GND}	Continuous Current Through GND	-50	mA
T_J	Operating Junction Temperature	-40 to +150	$^{\circ}C$
T_{STG}	Storage Temperature	-65 to +150	$^{\circ}C$

- Notes:
- Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
 - Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

Recommended Operating Conditions (Note 8)

Symbol	Parameter		Min	Max	Unit
V_{CC}	Operating Voltage	—	0.8	3.6	V
V_I	Input Voltage		0	3.6	V
V_O	Output Voltage		0	V_{CC}	V
I_{OH}	High-Level Output Current	$V_{CC} = 0.8V$	—	-20	μA
		$V_{CC} = 1.1V$	—	-1.1	mA
		$V_{CC} = 1.4V$	—	-1.7	
		$V_{CC} = 1.65V$	—	-1.9	
		$V_{CC} = 2.3V$	—	-3.1	
		$V_{CC} = 3.0V$	—	-4	
I_{OL}	Low-Level Output Current	$V_{CC} = 0.8V$	—	20	μA
		$V_{CC} = 1.1V$	—	1.1	mA
		$V_{CC} = 1.4V$	—	1.7	
		$V_{CC} = 1.65V$	—	1.9	
		$V_{CC} = 2.3V$	—	3.1	
		$V_{CC} = 3.0V$	—	4	
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate	$V_{CC} = 0.8V$ to $3.6V$	—	200	ns/V
T_A	Operating Free-Air Temperature	—	-40	+125	$^{\circ}C$

Note: 8. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics

Symbol	Parameter	Test Conditions	V _{CC}	T _A = +25°C		T _A = -40°C to +85°C		Unit
				Min	Max	Min	Max	
V _{IH}	High-Level Input Voltage	—	0.8V to 1.65V	0.80 x V _{CC}	—	0.80 x V _{CC}	—	V
		—	1.65V to 1.95V	0.65 x V _{CC}	—	0.65 x V _{CC}	—	
		—	2.3V to 2.7V	1.6	—	1.6	—	
		—	3.0V to 3.6V	2.0	—	2.0	—	
V _{IL}	Low-Level Input Voltage	—	0.8V to 1.65V	—	0.30 x V _{CC}	—	0.30 x V _{CC}	V
		—	1.65V to 1.95V	—	0.35 x V _{CC}	—	0.35 x V _{CC}	
		—	2.3V to 2.7V	—	0.7	—	0.7	
		—	3.0V to 3.6V	—	0.9	—	0.9	
V _{OH}	High-Level Output Voltage	I _{OH} = -20μA	0.8V to 3.6V	V _{CC} - 0.1	—	V _{CC} - 0.1	—	V
		I _{OH} = -1.1mA	1.1V	0.75 x V _{CC}	—	0.7 x V _{CC}	—	
		I _{OH} = -1.7mA	1.4V	1.11	—	1.03	—	
		I _{OH} = -1.9mA	1.65V	1.32	—	1.3	—	
		I _{OH} = -2.3mA	2.3V	2.05	—	1.97	—	
		I _{OH} = -3.1mA		1.9	—	1.85	—	
		I _{OH} = -2.7mA	3V	2.72	—	2.67	—	
		I _{OH} = -4mA		2.6	—	2.55	—	
V _{OL}	Low-Level Input Voltage	I _{OL} = 20μA	0.8V to 3.6V	—	0.1	—	0.1	V
		I _{OL} = 1.1mA	1.1V	—	0.3 x V _{CC}	—	0.3 x V _{CC}	
		I _{OL} = 1.7mA	1.4V	—	0.31	—	0.37	
		I _{OL} = 1.9mA	1.65V	—	0.31	—	0.35	
		I _{OL} = 2.3mA	2.3V	—	0.31	—	0.33	
		I _{OL} = 3.1mA		—	0.44	—	0.45	
		I _{OL} = 2.7mA	3V	—	0.31	—	0.33	
		I _{OL} = 4mA		—	0.44	—	0.45	
I _I	Input Current	A or B Input V _I = GND to 3.6V	0V to 3.6V	—	± 0.1	—	± 0.5	μA
I _{OFF}	Power Down Leakage Current	V _I or V _O = 0V to 3.6V	0V	—	± 0.2	—	± 0.6	μA
ΔI _{OFF}	Delta Power Down Leakage Current	V _I or V _O = 0V to 3.6V	0V to 0.2V	—	± 0.2	—	± 0.6	μA
I _{CC}	Supply Current	V _I = GND or V _{CC} , I _O = 0	0.8V to 3.6V	—	0.5	—	0.9	μA
ΔI _{CC}	Additional Supply Current	One Input at V _{CC} - 0.6V Other Inputs at V _{CC} or GND	3.3V	—	40	—	50	μA

Electrical Characteristics (continued)

Symbol	Parameter	Test Conditions	V _{CC}	T _A = -40°C to +125°C		Unit
				Min	Max	
V _{IH}	High-Level Input Voltage	—	0.8V to 1.65V	0.80 x V _{CC}	—	V
		—	1.65V to 1.95V	0.70 x V _{CC}	—	
		—	2.3V to 2.7V	1.6	—	
		—	3.0V to 3.6V	2.0	—	
V _{IL}	Low-Level Input Voltage	—	0.8V to 1.65V	—	0.25 x V _{CC}	V
		—	1.65V to 1.95V	—	0.30 x V _{CC}	
		—	2.3V to 2.7V	—	0.7	
		—	3.0V to 3.6V	—	0.9	
V _{OH}	High-Level Output Voltage	I _{OH} = -20μA	0.8V to 3.6V	V _{CC} - 0.11	—	V
		I _{OH} = -1.1mA	1.1V	0.6 x V _{CC}	—	
		I _{OH} = -1.7mA	1.4V	0.93	—	
		I _{OH} = -1.9mA	1.65V	1.17	—	
		I _{OH} = -2.3mA	2.3V	1.77	—	
		I _{OH} = -3.1mA		1.67	—	
		I _{OH} = -2.7mA	3V	2.40	—	
		I _{OH} = -4mA		2.30	—	
V _{OL}	Low-Level Input Voltage	I _{OL} = 20μA	0.8V to 3.6V	—	0.11	V
		I _{OL} = 1.1mA	1.1V	—	0.33 x V _{CC}	
		I _{OL} = 1.7mA	1.4V	—	0.41	
		I _{OL} = 1.9mA	1.65V	—	0.39	
		I _{OL} = 2.3mA	2.3V	—	0.36	
		I _{OL} = 3.1mA		—	0.50	
		I _{OL} = 2.7mA	3V	—	0.36	
		I _{OL} = 4mA		—	0.50	
I _I	Input Current	A or B Input, V _I = GND to 3.6V	0V to 3.6V	—	± 0.75	μA
I _{OFF}	Power Down Leakage Current	V _I or V _O = 0V to 3.6V	0V	—	± 1.0	μA
ΔI _{OFF}	Delta Power Down Leakage Current	V _I or V _O = 0V to 3.6V	0V to 0.2V	—	± 2.5	μA
I _{CC}	Supply Current	V _I = GND or V _{CC} , I _O = 0	0.8V to 3.6V	—	3.0	μA
ΔI _{CC}	Additional Supply Current	Input at V _{CC} - 0.6V Other Inputs at V _{CC} or GND	3.3V	—	75	μA

Operating and Package Characteristics (@T_A = +25°C, unless otherwise specified.)

Parameter		Test Conditions		V _{CC}	Typ	Unit
C _{pd}	Power Dissipation Capacitance	f = 1MHz No Load		0.8V	5.1	pF
				1.2V ± 0.1V	5.2	
				1.5V ± 0.1V	5.2	
				1.8V ± 0.15V	5.5	
				2.5V ± 0.2V	5.7	
				3.3V ± 0.3V	6.0	
C _i	Input Capacitance	V _I = V _{CC} or GND		0V or 3.3V	2.0	pF
θ _{JA}	Thermal Resistance Junction-to-Ambient	X2-DFN1210-8	(Note 9)	—	+395	°C/W
θ _{JC}	Thermal Resistance Junction-to-Case	X2-DFN1210-8	(Note 9)	—	+236	°C/W

Note: 9. Test condition, X2-DFN1210-8 device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Switching Characteristics

 $C_L = 5\text{pF}$, See Figure 1

Parameter	From Input	To Output	V _{CC}	T _A = +25°C			T _A = -40°C to +85°C		T _A = -40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t _{pd}	A or B	Y	0.8V	—	24.4	—	—	—	—	—	ns
			1.2V ± 0.1V	2.3	5.9	14.4	2.1	15.3	2.1	16.6	
			1.5V ± 0.1V	1.8	4.1	7.7	1.6	8.8	1.6	9.7	
			1.8V ± 0.15V	1.5	3.3	5.9	1.4	6.9	1.4	7.6	
			2.5V ± 0.2V	1.2	2.6	4.4	1.1	5.3	1.1	5.9	
			3.3V ± 0.3V	1.0	2.3	4.0	0.9	4.7	0.9	5.2	

 $C_L = 10\text{p}$, See Figure 1

Parameter	From Input	To Output	V _{CC}	T _A = +25°C			T _A = -40°C to +85°C		T _A = -40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t _{pd}	A or B	Y	0.8V	—	28.4	—	—	—	—	—	ns
			1.2V ± 0.1V	2.6	6.8	16.3	2.4	17.3	2.4	18.8	
			1.5V ± 0.1V	2.2	4.8	8.7	1.9	10.0	1.9	11.0	
			1.8V ± 0.15V	1.8	3.9	6.7	1.7	8.0	1.7	8.8	
			2.5V ± 0.2V	1.5	3.1	5.2	1.4	6.2	1.4	6.9	
			3.3V ± 0.3V	1.3	2.9	4.8	1.3	5.6	1.3	6.2	

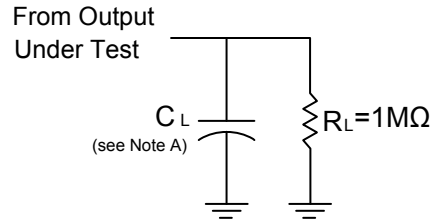
 $C_L = 15\text{pF}$, See Figure 1

Parameter	From Input	To Output	V _{CC}	T _A = +25°C			T _A = -40°C to +85°C		T _A = -40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t _{pd}	A or B	Y	0.8V	—	32.4	—	—	—	—	—	ns
			1.2V ± 0.1V	3.0	7.6	18.2	2.7	19.4	2.7	21.0	
			1.5V ± 0.1V	2.4	5.3	9.6	2.2	11.3	2.2	12.5	
			1.8V ± 0.15V	2.1	4.4	7.5	1.9	9.0	1.9	9.9	
			2.5V ± 0.2V	1.8	3.6	5.9	1.6	7.0	1.6	7.7	
			3.3V ± 0.3V	1.4	3.3	5.4	1.4	6.4	1.4	7.1	

 $C_L = 30\text{pF}$, See Figure 1

Parameter	From Input	To Output	V _{CC}	T _A = +25°C			T _A = -40°C to +85°C		T _A = -40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t _{pd}	A or B	Y	0.8V	—	44.3	—	—	—	—	—	ns
			1.2V ± 0.1V	3.9	9.9	23.7	3.5	25.8	3.5	27.9	
			1.5V ± 0.1V	3.2	6.9	12.5	2.8	14.8	2.8	16.3	
			1.8V ± 0.15V	2.8	5.7	9.8	2.5	11.7	2.5	12.9	
			2.5V ± 0.2V	2.4	4.7	7.6	2.2	9.1	2.2	10.1	
			3.3V ± 0.3V	1.9	4.4	7.1	1.8	8.3	1.8	9.2	

Parameter Measurement Information



V _{CC}	Inputs		V _M	C _L
	V _I	t _r /t _f		
0.8V	V _{CC}	≤3ns	V _{CC} /2	5, 10, 15, 30pF
1.2V ± 0.1V	V _{CC}	≤3ns	V _{CC} /2	5, 10, 15, 30pF
1.5V ± 0.1V	V _{CC}	≤3ns	V _{CC} /2	5, 10, 15, 30pF
1.8V ± 0.15V	V _{CC}	≤3ns	V _{CC} /2	5, 10, 15, 30pF
2.5V ± 0.2V	V _{CC}	≤3ns	V _{CC} /2	5, 10, 15, 30pF
3.3V ± 0.3V	V _{CC}	≤3ns	V _{CC} /2	5, 10, 15, 30pF

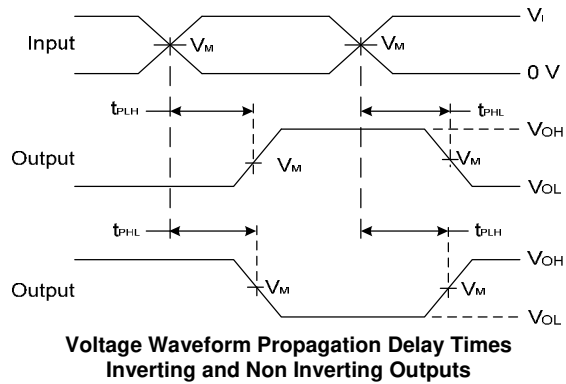
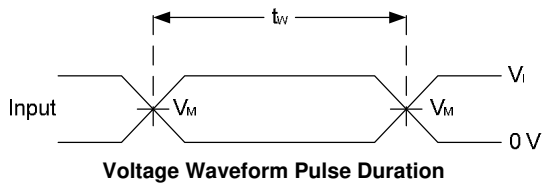


Figure 1 Load Circuit and Voltage Waveforms

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{PD} .

Marking Information

X2-DFN1210-8

(Top View)

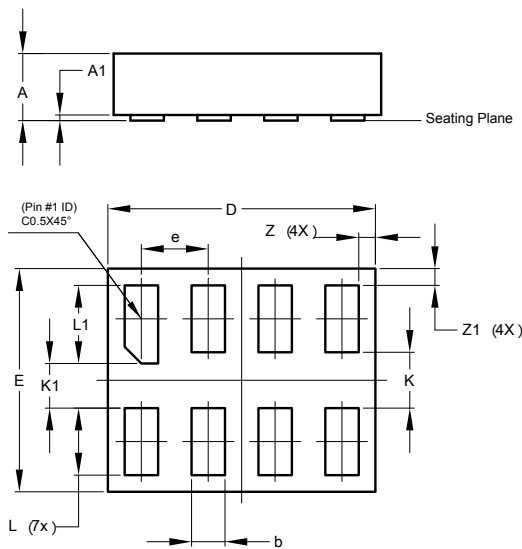


- XX : Identification Code
- Y : Year : 0~9
- W : week : A~Z : 1~26 week
a~z: 27-52 week
z represents 52 and 53 week
- X : week : A~Z : Internal code

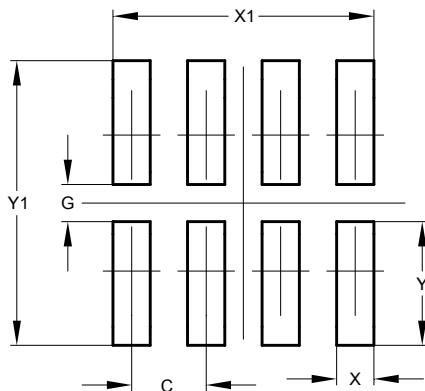
Part Number	Package	Identification Code
74AUP2G86RA3-7	X2-DFN1210-8	FT

X2-DFN1210-8 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



X2-DFN1210-8			
Dim	Min	Max	Typ
A	-	0.35	0.30
A1	0	0.03	0.02
b	0.10	0.20	0.15
D	1.15	1.25	1.20
E	0.95	1.05	1.00
e	-	-	0.30
K	-	-	0.25
K1	-	-	0.20
L	0.25	0.35	0.30
L1	0.30	0.40	0.35
Z	0.050	0.100	0.075
Z1	0.050	0.100	0.075
All Dimensions in mm			



Dimensions	Value (in mm)
C	0.300
G	0.150
X	0.150
X1	1.050
Y	0.500
Y1	1.150

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